



- Reduces Corrosion
- Quick Installation
- Dust Free

CONDUFORM

Protecting networks and assets

ConduForm™ is a dust free, conductive carbonaceous backfill material that is installed as a liquid and cures as a solid. **ConduForm™** is designed for applications where overburden is shallow or non-existent. It provides superior corrosion and theft protection. It can be poured on exposed rock surfaces to protect conductors and improve grounding where trenching is not possible. With an expected in-service lifetime that is up to 20x the industry standard, electrode corrosion is virtually eliminated. **ConduForm™** offers many advantages:

- Pourable – no need to transfer to mixing container
- 99.9% reduction in corrosion of copper
- Environmentally friendly
- Extends the life of the grounding system
- Liquid installation adheres well to native material
- Adheres to bedrock and other bare surfaces
- Cures as a black impermeable solid

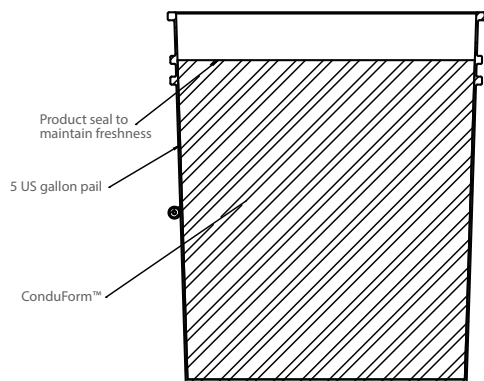


ConduForm™ is a low slump, formable product that sets up within 3 hours of installation and forms a strong bond to the native material. It is an environmentally friendly solution that can withstand freeze-thaw cycling and helps to prevent theft and accidental damage of the conductor. It is sold in a 5 US gallon container.

Applications

- Grounding on bedrock.
- Rocky shoreline grounding.

Product Specifications



Properties

Appearance

Odor

Permeability to Water

Hygroscopic Property

Resistivity

Electrolytic Corrosion Resistance

Freeze-Thaw Withstand

Typical Value

Cured: Black Solid
Uncured: Dark Blue Slurry (granular)
Slight, Sweet Odor
6.5×10^{-6} cm/s (ASTM 5084)
34%
20 $\Omega \cdot \text{cm}$
99.9%
> 25 Years (testing ongoing)

Values subject to change.

Updated: 6/25/2018